40 V, 8.0 A, Low V_{CE(sat)} **NPN Transistor**

ON Semiconductor's e²PowerEdge family of low V_{CE(sat)} transistors are miniature surface mount devices featuring ultra low saturation voltage (V_{CE(sat)}) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

• This is a Pb-Free Device

MAXIMUM RATINGS (T_A = 25°C)

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V _{CEO}	40	Vdc
Collector-Base Voltage	V _{CBO}	40	Vdc
Emitter-Base Voltage	V _{EBO}	6.0	Vdc
Collector Current - Continuous	I _C	6.0	Adc
Collector Current - Peak	I _{CM}	8.0	Α
Electrostatic Discharge	ESD	HBM Class 3B MM Class C	

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation, T _A = 25°C Derate above 25°C	P _D (Note 1)	830 6.7	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 1)	150	°C/W
Total Device Dissipation, T _A = 25°C Derate above 25°C	P _D (Note 2)	1.4 11.1	W mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 2)	90	°C/W
Thermal Resistance, Junction-to-Lead #1	R _{θJL} (Note 2)	15	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

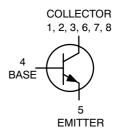
- 1. FR-4 @ 100 mm², 1 oz copper traces. 2. FR-4 @ 500 mm², 1 oz copper traces.



ON Semiconductor®

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40 VOLTS, 8.0 AMPS NPN LOW $V_{CE(sat)}$ TRANSISTOR EQUIVALENT $R_{DS(on)}$ 31 m Ω





ChipFET™ **CASE 1206A** STYLE 4

MARKING DIAGRAM

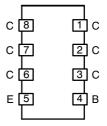


VB = Specific Device Code

M = Month Code

= Pb-Free Package

PIN CONNECTIONS



ORDERING INFORMATION

Device	Package	Shipping [†]
NSS40601CF8T1G	ChipFET (Pb-Free)	3000/ Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Typical	Max	Unit
OFF CHARACTERISTICS	1				II.
Collector-Emitter Breakdown Voltage ($I_C = 10 \text{ mAdc}, I_B = 0$)	V _{(BR)CEO}	40	-	-	Vdc
Collector-Base Breakdown Voltage $(I_C = 0.1 \text{ mAdc}, I_E = 0)$	V _{(BR)CBO}	40	-	-	Vdc
Emitter-Base Breakdown Voltage $(I_E = 0.1 \text{ mAdc}, I_C = 0)$	V _{(BR)EBO}	6.0	-	-	Vdc
Collector Cutoff Current (V _{CB} = 40 Vdc, I _E = 0)	I _{CBO}	-	-	0.1	μAdc
Emitter Cutoff Current (V _{EB} = 6.0 Vdc)	I _{EBO}	-	-	0.1	μAdc
ON CHARACTERISTICS	<u>. </u>				
DC Current Gain (Note 3) ($I_C = 10 \text{ mA}, V_{CE} = 2.0 \text{ V}$) ($I_C = 500 \text{ mA}, V_{CE} = 2.0 \text{ V}$) ($I_C = 1.0 \text{ A}, V_{CE} = 2.0 \text{ V}$) ($I_C = 2.0 \text{ A}, V_{CE} = 2.0 \text{ V}$) ($I_C = 3.0 \text{ A}, V_{CE} = 2.0 \text{ V}$)	h _{FE}	200 200 200 200 200 200	- - 395 - -	- - - -	
Collector-Emitter Saturation Voltage (Note 3) ($I_C = 0.1 \text{ A}$, $I_B = 0.010 \text{ A}$) ($I_C = 1.0 \text{ A}$, $I_B = 0.100 \text{ A}$) ($I_C = 1.0 \text{ A}$, $I_B = 0.010 \text{ A}$) ($I_C = 2.0 \text{ A}$, $I_B = 0.020 \text{ A}$) ($I_C = 3.0 \text{ A}$, $I_B = 0.030 \text{ A}$) ($I_C = 4.0 \text{ A}$, $I_B = 0.400 \text{ A}$)	VCE(sat)	- - - -	0.008 0.031 0.060 0.075 0.100 0.090	0.010 0.075 0.075 0.110 0.150 0.135	V
Base-Emitter Saturation Voltage (Note 3) $(I_C = 1.0 \text{ A}, I_B = 0.01 \text{ A})$	V _{BE(sat)}	-	0.760	0.900	V
Base-Emitter Turn-on Voltage (Note 3) (I _C = 2.0 A, V _{CE} = 2.0 V)	V _{BE(on)}	-	0.720	0.900	V
Cutoff Frequency (I _C = 100 mA, V _{CE} = 5.0 V, f = 100 MHz)	f _T	140	-	-	MHz
Input Capacitance (V _{EB} = 0.5 V, f = 1.0 MHz)	Cibo	-	-	1200	pF
Output Capacitance (V _{CB} = 3.0 V, f = 1.0 MHz)	Cobo	-	-	100	pF
SWITCHING CHARACTERISTICS	<u> </u>				
Delay (V _{CC} = 30 V, I _C = 750 mA, I _{B1} = 15 mA)	t _d	-	-	110	ns
Rise ($V_{CC} = 30 \text{ V}, I_C = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$)	t _r	-	-	130	ns
Storage (V _{CC} = 30 V, I _C = 750 mA, I _{B1} = 15 mA)	t _s	-	-	1400	ns
Fall (V _{CC} = 30 V, I _C = 750 mA, I _{B1} = 15 mA)	t _f	-	-	130	ns

^{3.} Pulsed Condition: Pulse Width = 300 $\mu sec,$ Duty Cycle \leq 2%.

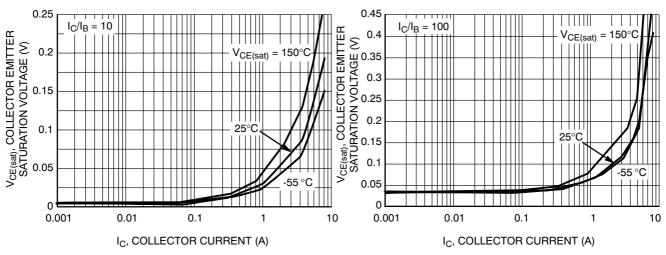


Figure 1. Collector Emitter Saturation Voltage vs. Collector Current

Figure 2. Collector Emitter Saturation Voltage vs. Collector Current

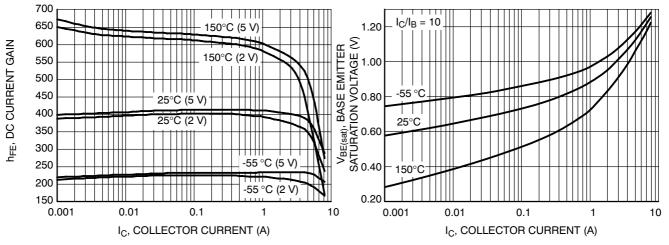


Figure 3. DC Current Gain vs. Collector Current

V_{CE}, COLLECTOR-EMITTER VOLTAGE (V) V_{BE(on)}, BASE EMITTER TURN-ON VOLTAGE (V) 1.0 $V_{CE} = 2.0 \text{ V}$ 0.9 -55 °C 0.8 0.7 0.6 0.5 150°C 0.4 0.3 0.2 0.1 0.001 0.01 0.1 1 10 IC, COLLECTOR CURRENT (A)

Figure 5. Base Emitter Turn-On Voltage vs.
Collector Current

Figure 4. Base Emitter Saturation Voltage vs.
Collector Current

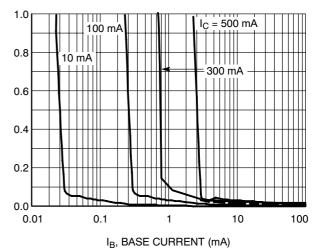


Figure 6. Saturation Region

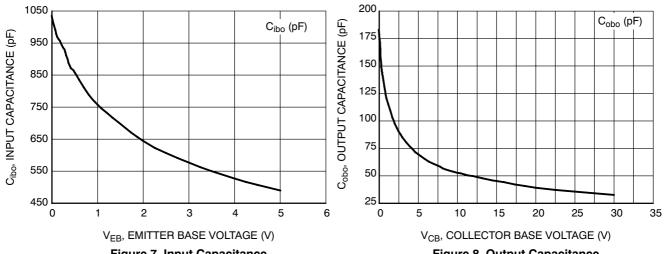


Figure 7. Input Capacitance

Figure 8. Output Capacitance

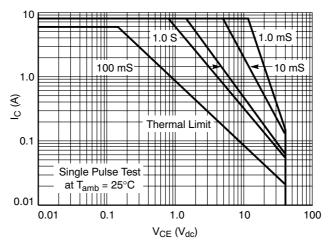
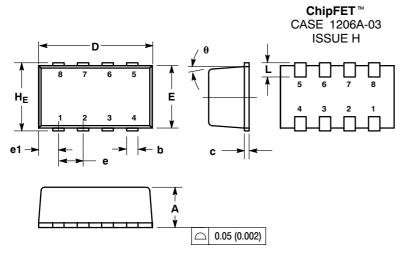


Figure 9. Safe Operating Area

PACKAGE DIMENSIONS



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

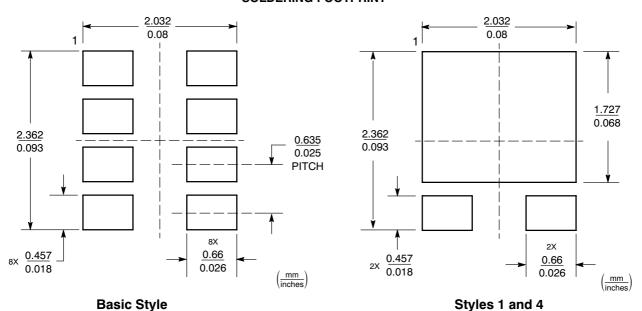
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 MOLD GATE BURRS SHALL NOT EXCEED 0.13 MM PER SIDE.
 LEADFRAME TO MOLDED BODY OFFSET IN HORIZONTAL
 AND VERTICAL SHALL NOT EXCEED 0.08 MM.
 DIMENSIONS A AND B EXCLUSIVE OF MOLD GATE BURRS.
 NO MOLD FLASH ALLOWED ON THE TOP AND BOTTOM LEAD SURFACE.

	MILLIMETERS				INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.00	1.05	1.10	0.039	0.041	0.043
b	0.25	0.30	0.35	0.010	0.012	0.014
С	0.10	0.15	0.20	0.004	0.006	0.008
D	2.95	3.05	3.10	0.116	0.120	0.122
E	1.55	1.65	1.70	0.061	0.065	0.067
е	0.65 BSC			0.025 BSC		
e1	0.55 BSC			0.022 BSC		
L	0.28	0.35	0.42	0.011	0.014	0.017
HE	1.80	1.90	2.00	0.071	0.075	0.079
θ		5° NOM		5° NOM		

- STYLE 4:
 PIN 1. COLLECTOR
 2. COLLECTOR
 3. COLLECTOR
 4. BASE
 5. EMITTER
 6. COLLECTOR

 - 7. COLLECTOR 8. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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